



Sept 26, 2017

LOW OUTGAS ADHESIVES

The following qualify as low outgas adhesives by TGA (thermal gravimetric analysis).

Telcordia GR-1221: 50-150 °C @ 5 °C/min, <0.1% for thermal cure, <0.25% for photo-cure

MIL-STD 883/5011: room temperature to 210 °C at 10 or 20 °C/min, 10-20 mL nitrogen flow, <1.0% loss at 200 °C

Outgas weight % loss

UV-Cure epoxy adhesives (photo-cured)

Adhesive	Telcordia GR-1221	MIL-STD 883/5011
A535-A	0.23	0.60
A535-AN	0.13	0.19
A586	0.12	0.23
A1432	0.16	0.18

Dual-Cure epoxy adhesives (photo-cured with thermal post cure)

Adhesive	Telcordia GR-1221	MIL-STD 883/5011
A535-AT	0.01	0.05
A539-DM	0.08	0.18
A1702-A	0.01	0.05
A1705-A	0.04	0.08
A1708-A	0.03	0.08
A1705-TX	0.01	0.03
A1719-TX	0.07	0.41
A1760-TX	0.02	0.09
A1864-TX	0.07	0.17
TCL202	0.07	0.11
TCL203	0.06	0.11
TCR1002	0.03	0.21
TCR1003	0.09	0.06
	Thermal Cure Only	
TCL104	0.08	0.11
TCL105	0.07	0.11